

650V N-Channel Silicon Carbide Power MOSFET

RoHS

FEATURES

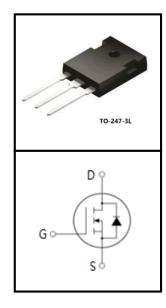
- Low On-Resistance
- Low Capacitance
- Avalanche Ruggedness
- Halogen Free, RoHS Compliant

BENEFITS

- Higher System Efficiency
- Parallel Device Convenience
- High Temperature Application
- High Frequency Operation

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Power Factor Correction (PFC)
- Uninterruptible Power Supply (UPS)
- EV Charging station & Motor Drives
- Solar/ Wind Renewable Energy
- Power Inverters & DC/DC Converters



Device Marking and Package Information					
Device	Package	Marking			
C2M065W030	TO-247-3L	C2M065W030			

Halogen free

Absolute Maximum Ratings $T_c = 25^{\circ}C$, unless otherwise noted								
Parameter	Symbol Test Conditions		Value	Unit				
Drain-Source Voltage	V _{DSS}	VGS=0V, IDS=100µA	650	V				
Continuous Drain Current	I _D	VGS=20V, Tc=25°C	100	,				
Pulsed Drain Current	I _{DM}	tew limitation per Fig.17	400	A				
Power Dissipation	P _D	Tc=25°C	338	W				
Recommend Gate Source Voltage	VGS, op	Static	-5/+20	v				
Maximum Gate Source Voltage	Vgs, max	AC (f > 1Hz)	-10/+25	V				
Soldering Temperature	T∟		260					
Operating Junction and Storage Temperature Range	T _J , T _{stg}		-55/+150	°C				

Thermal Resistance						
Parameter Symbol Value Unit						
Thermal Resistance, Junction-to-Case	R _{thJC}	0.37	K/W			



C2M065W030

Paramotor	Currence al	Toot Conditions	Value				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0V, I_D = 100\mu A$	650			V	
		$V_{DS} = 650V, V_{GS} = 0V, T_{J} = 25^{\circ}C$ <1		100			
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 650V, V _{GS} = 0V, T _J = 150°C		10	500	μA	
Gate-Source Leakage	I _{GSS}	$V_{GS} = 20V, V_{DS} = 0V$			200	nA	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = 10V, I_D = 5mA$	2		3.5	V	
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 20V, I _D = 30A		30	36	mΩ	
Dynamic							
Input Capacitance	C _{iss}	V _{GS} = 0V		2333		рF	
Output Capacitance	C _{oss}	V _{DS} = 400V f = 1.0MHz		264			
Reverse Transfer Capacitance	C _{rss}	Vac=25mV		46			
Effective Output Capacitance, Energy Related	Co(er)	VGS=0V V _{DS} =0 to 450V		187			
Effective Output Capacitance, Time Related	Co(tr)	I _D =const., VGs=0V V _{DS} =0 to 450V		253			
Total Gate Charge	Q _g			140		nC	
Gate-Source Charge	Q _{gs}	V _{DS} =300V, VGS=0/+15V,		26			
Gate-Drain Charge	Q _{gd}	I _D =50A		69			
Gate plateau voltage	Vpl			10		V	
Turn-on Delay Time	t _{d(on)}			45			
Turn-on Rise Time	t _r	V _{DS} =300V V _{GS} =0/15V		107			
Turn-off Delay Time	t _{d(off)}	$I_D = 50A$ RG(ext) = 2.5 Ω		67		ns	
Turn-off Fall Time	t _f			16			
Coss Stored Energy	Eoss	V _{GS} =0V, V _{DS} =650V f =1MHz, VAC=25mV		119			
Turn-on Switching Energy	Eon	V _{DS} =650V,		194*		μJ	
Turn-off Switching Energy	Eoff	V _{GS} =0/15V, I _D =20A, RG(ext)= 2.5Ω		326*			
Internal Gate Resistance	RG(int.)	f =1MHz, VAC=25mV		3		Ω	

*Base on the results of calculation, note that the energy loss caused by the reverse recovery of FWD is not included in E on .



C2M065W030

Built-in SiC Diode Characteristics								
Continuous Diode Forward Current	۱ _s	$V_{GS} = 0V$		100		А		
Inverse Diode Forward Voltage	V _{SD}	I _{SD} = 30A, V _{GS} = -5V			6	V		
Reverse Recovery Time	t _{rr}			72		ns		
Reverse Recovery Charge	Q _{rr}	I _F = 25A, V _{DS} =150V, di _F /dt =500A /μs		181		nC		
Peak Reverse Recovery Current	IRM			4.6		А		

Typical Device Performance

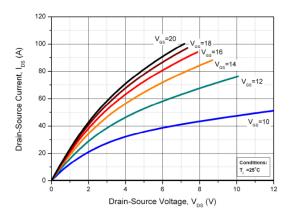


Fig. 1 Forward Output Characteristics at $T_j = 25^{\circ}C$

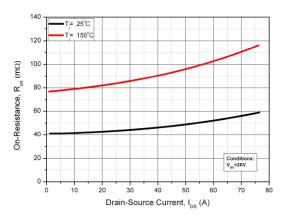
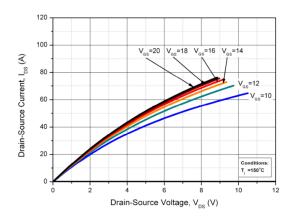
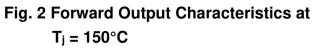


Fig. 3 On-Resistance vs. Drain Current for Various T_j





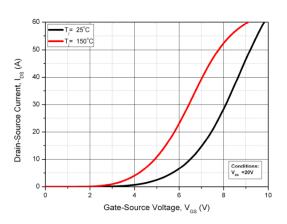


Fig. 4 Transfer Characteristics for Various T_j



Typical Device Performance

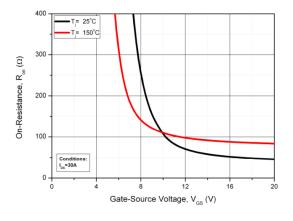


Fig. 5 On-Resistance vs. Gate Voltage for Various T_j

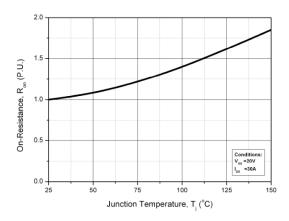
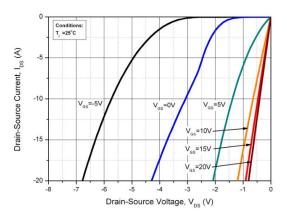


Fig. 7 Normalized On-Resistance vs. Temperature





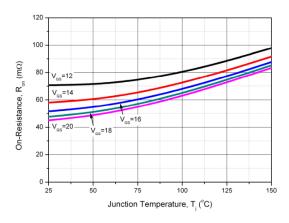


Fig. 6 On-Resistance vs. Temperature for Various Gate Voltage

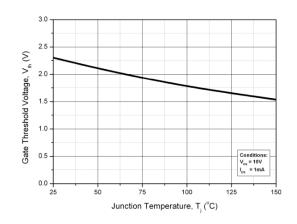
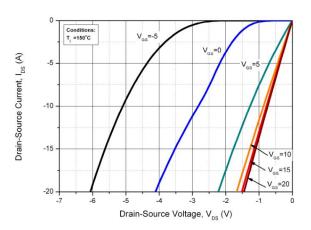


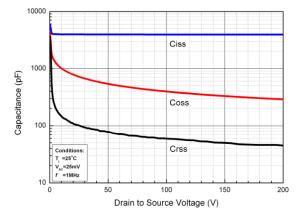
Fig. 8 Threshold Voltage vs. Temperature

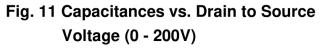






Typical Device Performance





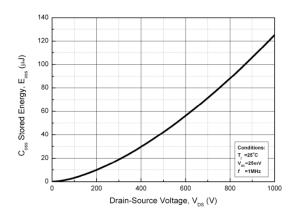


Fig. 13 Output Capacitor Stored Energy

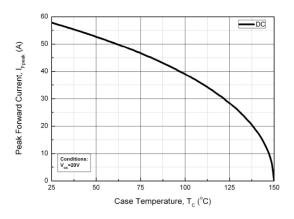


Fig. 15 Drain Current Derating vs. Case Temperature

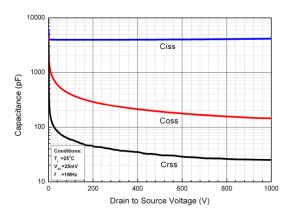


Fig. 12 Capacitances vs. Drain to Source Voltage (0 - 1000V)

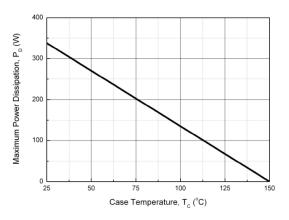
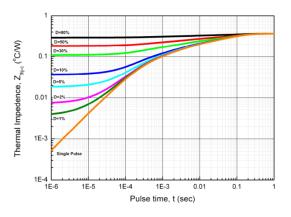


Fig. 14 Maximum Power Dissipation Derating vs. Case Temperature









Typical Device Performance

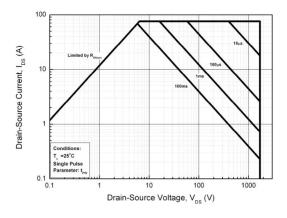


Fig. 17 Safe Operating Area

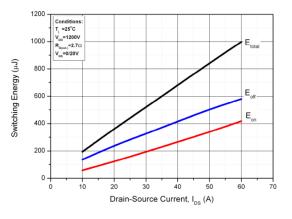


Fig. 19 Clamped Inductive Switching Energy vs. Drain Current (V_{DD}=1200V)*

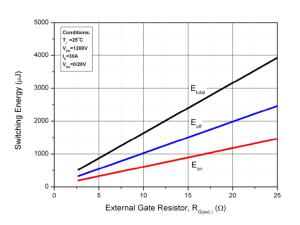


Fig. 21 Clamped Inductive Switching Energy vs. External Gate Resistor (R_{G(ext.)})*

*Base on the results of calculation, note that the energy loss caused by the reverse recovery of FWD is not included in E on .

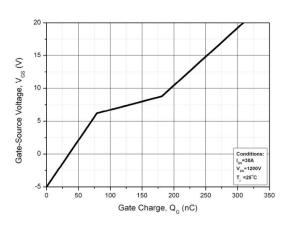


Fig. 18 Gate Charge Characteristics

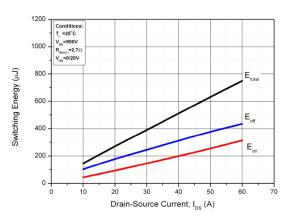
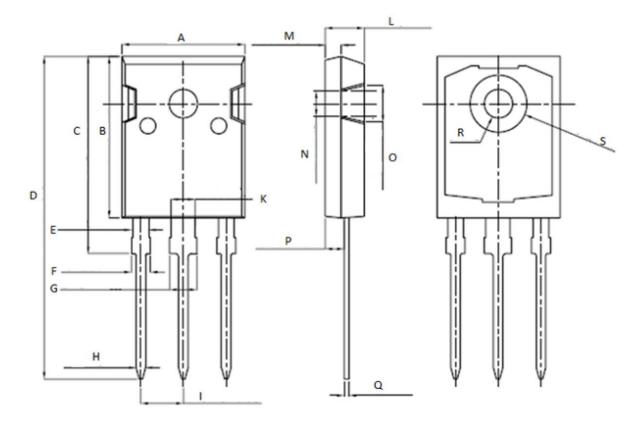


Fig. 20 Clamped Inductive Switching Energy vs. Drain Current (V_{DD}=900V)*





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Unit: mm			Unit: mm			
Symbol	Min.	Max.	Symbol	Min.	Max.	
Α	15.95	16. 25	K	2.90	3.10	
В	20.85	21. 25	L	4.90	5.30	
C	20.95	21.35	М	1.90	2.10	
D	40.5	40.9	Ν	4.50	4. 70	
E	1.9	2.1	0	5.40	5.60	
F	2.1	2. 25	Р	2.29	2.49	
G	3.1	3. 25	Q	0. 51	0. 71	
Н	1.1	1.3	R	φ3.5	φ3.7	
	5.40	5.50	S	φ7.1	φ7.3	

*The information provided herein is subject to change without notice.



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